### INTEGRATED CIRCUITS

# DATA SHEET

## **MB2244**

16-bit buffer/line driver (3-State)

Product specification Supersedes data of 1993 Aug 24 IC23 Data Handbook





### 16-bit buffer/line driver (3-State)

**MB2244** 

#### **FEATURES**

- 16-bit bus interface
- Multiple V<sub>CC</sub> and GND pins minimize switching noise
- Power-up 3-State
- 3-State buffers
- Output capability: +64 mA/-32mA
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- Inputs are disabled during 3-State mode

#### **DESCRIPTION**

The MB2244 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The MB2244 device is an 16-bit buffer that is ideal for driving bus lines. The device features four Output Enables ( $1\overline{OE}$ ,  $2\overline{OE}$ ,  $3\overline{OE}$ ,  $4\overline{OE}$ ), each controlling four of the 3-State outputs.

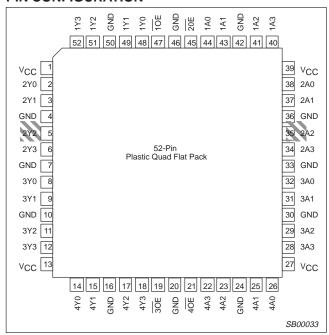
#### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	CONDITIONS T <sub>amb</sub> = 25°C; GND = 0V	TYPICAL	UNIT
<sup>†</sup> PLH <sup>†</sup> PHL	Propagation delay nAx to nYx	$C_L = 50pF; V_{CC} = 5V$	3.2 3.1	ns
C <sub>IN</sub>	Input capacitance	V <sub>I</sub> = 0V or V <sub>CC</sub>	4	pF
C <sub>OUT</sub>	Output capacitance	V <sub>O</sub> = 0V or V <sub>CC</sub> ; 3-State	7	pF
I <sub>CCZ</sub>	Total supply current	Outputs disabled; V <sub>CC</sub> = 5.5V	50	μΑ

#### ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
52-pin plastic Quad Flat Pack	-40°C to +85°C	MB2244 BB	MB2244 BB	SOT379-1

### **PIN CONFIGURATION**



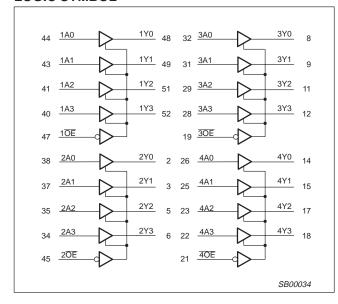
### **PIN DESCRIPTION**

PIN NUMBER	SYMBOL	NAME AND FUNCTION
44, 43, 41, 40, 38, 37, 35, 34, 32, 31, 29, 28, 26, 25, 23, 22	1A0 – 1A3, 2A0 – 2A3, 3A0 – 3A3, 4A0 – 4A3	Data inputs
48, 49, 51, 52, 2, 3, 5, 6, 8, 9, 11, 12, 14, 15, 17, 18	1Y0 - 1Y3, 2Y0 - 2Y3, 3Y0 - 3Y3, 4Y0 - 4Y3	Data outputs
47, 45, 19, 21	1 <u>0E</u> , 2 <u>0E</u> , 3 <u>0E</u> , 4 <u>0E</u>	Output enables
4, 7, 10, 16, 20, 24, 30, 33, 36, 42, 46, 50	GND	Ground (0V)
1, 13, 27, 39	V <sub>CC</sub>	Positive supply voltage

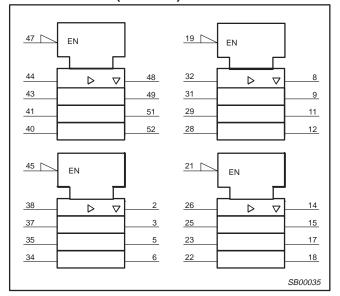
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#### LOGIC SYMBOL



### LOGIC SYMBOL (IEEE/IEC)



#### **FUNCTION TABLE**

INPU	JTS	OUTPUTS
nOE	nAx	nYx
L	L	L
L	Н	Н
Н	Х	Z

### ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +7.0	V
I <sub>IK</sub>	DC input diode current	V <sub>I</sub> < 0	-18	mA
VI	DC input voltage <sup>3</sup>		-1.2 to +7.0	V
lok	DC output diode current	V <sub>O</sub> < 0	-50	mA
V <sub>OUT</sub>	DC output voltage <sup>3</sup>	output in Off or High state	-0.5 to +5.5	V
l <sub>OUT</sub>	DC output current	output in Low state	128	mA
T <sub>stg</sub>	Storage temperature range		-65 to 150	°C

### NOTES:

- 1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	LIM	ITS	UNIT
		Min	Max	
V <sub>CC</sub>	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V <sub>CC</sub>	V
V <sub>IH</sub>	High-level input voltage	2.0		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
I <sub>OH</sub>	High-level output current		-32	mA
I <sub>OL</sub>	Low-level output current		64	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V
T <sub>amb</sub>	Operating free-air temperature range	-40	+85	°C

### DC ELECTRICAL CHARACTERISTICS

					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	Tai	<sub>mb</sub> = +25	°C	T <sub>amb</sub> =	-40°C 85°C	UNIT
			Min	Тур	Max	Min	Max	
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = 4.5V; I <sub>IK</sub> = -18mA		-0.9	-1.2		-1.2	V
		$V_{CC} = 4.5V$ ; $I_{OH} = -3mA$ ; $V_I = V_{IL}$ or $V_{IH}$	2.5	2.9		2.5		V
V <sub>OH</sub>	High-level output voltage	$V_{CC} = 5.0V$ ; $I_{OH} = -3mA$ ; $V_I = V_{IL}$ or $V_{IH}$	3.0	3.4		3.0		V
		$V_{CC} = 4.5V$ ; $I_{OH} = -32mA$ ; $V_I = V_{IL}$ or $V_{IH}$	2.0	2.4		2.0		V
V <sub>OL</sub>	Low-level output voltage	$V_{CC} = 4.5V$ ; $I_{OL} = 64mA$ ; $V_I = V_{IL}$ or $V_{IH}$		0.42	0.55		0.55	V
I <sub>I</sub>	Input leakage current	V <sub>CC</sub> = 5.5V; V <sub>I</sub> = GND or 5.5V		±0.01	±1.0		±1.0	μА
I <sub>OFF</sub>	Power-off leakage current	$V_{CC} = 0.0V$ ; $V_{O}$ or $V_{I} \le 4.5V$		±5.0	±100		±100	μА
I <sub>PU/PD</sub>	Power-up/down 3-State output current	$V_{\underline{CC}}$ = 2.0V; $V_{\underline{O}}$ = 0.5V; $V_{\underline{I}}$ = GND or $V_{\underline{CC}}$ ; $V_{\underline{OE}}$ = $V_{\underline{CC}}$		±5.0	±50		±50	μА
I <sub>OZH</sub>	3-State output High current	$V_{CC} = 5.5V; V_O = 2.7V; V_I = V_{IL} \text{ or } V_{IH}$		5.0	50		50	μΑ
I <sub>OZL</sub>	3-State output Low current	$V_{CC} = 5.5V; V_O = 0.5V; V_I = V_{IL} \text{ or } V_{IH}$		-5.0	-50		-50	μА
I <sub>CEX</sub>	Output High leakage current	$V_{CC} = 5.5V$ ; $V_O = 5.5V$ ; $V_I = GND$ or $V_{CC}$		5.0	50		50	μΑ
Io	Output current <sup>1</sup>	$V_{CC} = 5.5V; V_{O} = 2.5V$	-50	-100	-180	-50	-180	mA
I <sub>CCH</sub>		$V_{CC} = 5.5V$ ; Outputs High, $V_{I} = GND$ or $V_{CC}$		50	100		100	μА
I <sub>CCL</sub>	Quiescent supply current	$V_{CC}$ = 5.5V; Outputs Low, $V_{I}$ = GND or $V_{CC}$		48	60		60	mA
I <sub>CCZ</sub>		$V_{CC}$ = 5.5V; Outputs 3-State; $V_{I}$ = GND or $V_{CC}$		50	100		100	μА
Δl <sub>CC</sub>	Additional supply current per input pin <sup>2</sup>	Outputs enabled, one input at 3.4V, other inputs at $V_{CC}$ or GND; $V_{CC}$ = 5.5V		0.5	1.5		1.5	mA

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
This is the increase in supply current for each input at 3.4V.

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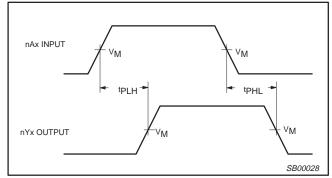
#### **AC CHARACTERISTICS**

GND = 0V;  $t_R$  =  $t_F$  = 2.5ns;  $C_L$  = 50pF,  $R_L$  = 500 $\Omega$ 

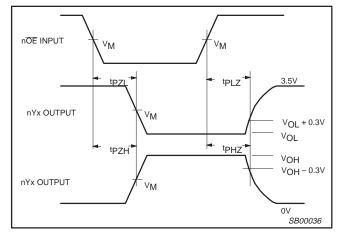
					LIMIT	rs		
SYMBOL	PARAMETER	WAVEFORM	T <sub>a</sub>	<sub>amb</sub> = +25° ' <sub>CC</sub> = +5.0'	C V	T <sub>amb</sub> = -40° V <sub>CC</sub> = +5.	°C to +85°C .0V ±0.5V	UNIT
			Min	Тур	Max	Min	Max	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay nAx to nYx	1	1.2 1.2	3.2 3.1	4.5 4.5	1.2 1.2	5.1 5.1	ns
t <sub>PZH</sub> t <sub>PZL</sub>	Output enable time to High and Low level	2	1.1 1.8	3.0 4.0	4.4 5.4	1.1 1.8	5.1 6.4	ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output disable time from High and Low level	2	1.6 1.7	4.0 3.4	5.6 5.0	1.6 1.7	6.2 5.6	ns

### **AC WAVEFORMS**

 $V_M = 1.5V$ ,  $V_{IN} = GND$  to 3.0V



Waveform 1. Input (An) to Output (Yn) Propagation Delays



Waveform 2. 3-State Output Enable and Disable Times

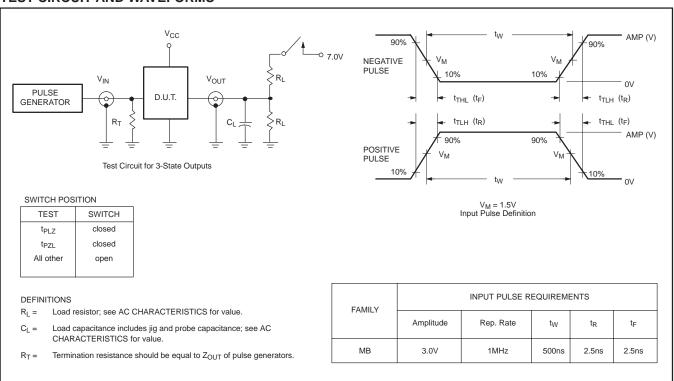
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### 16-bit buffer/line driver (3-State)

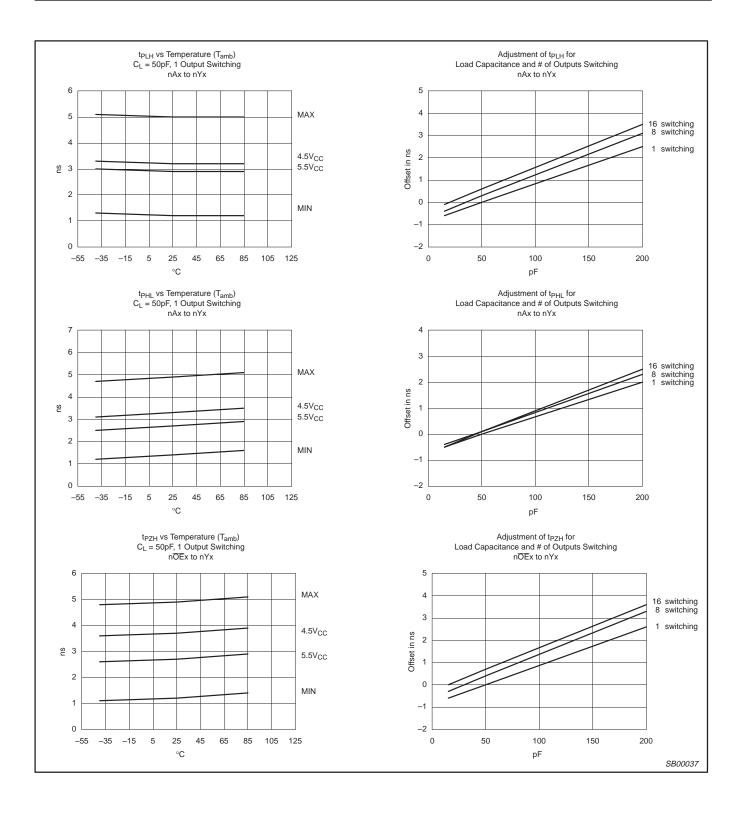
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### **TEST CIRCUIT AND WAVEFORMS**

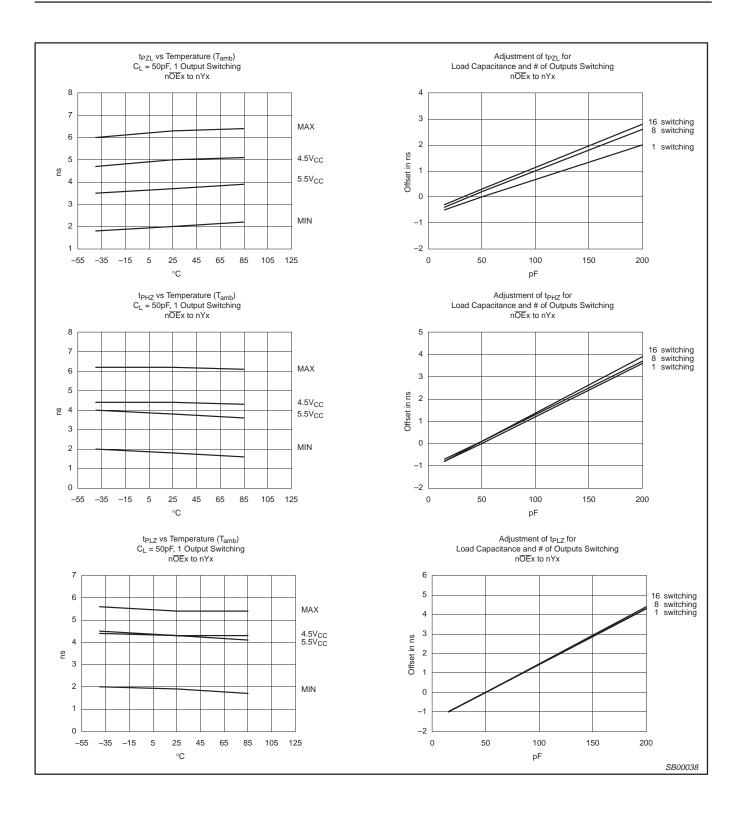


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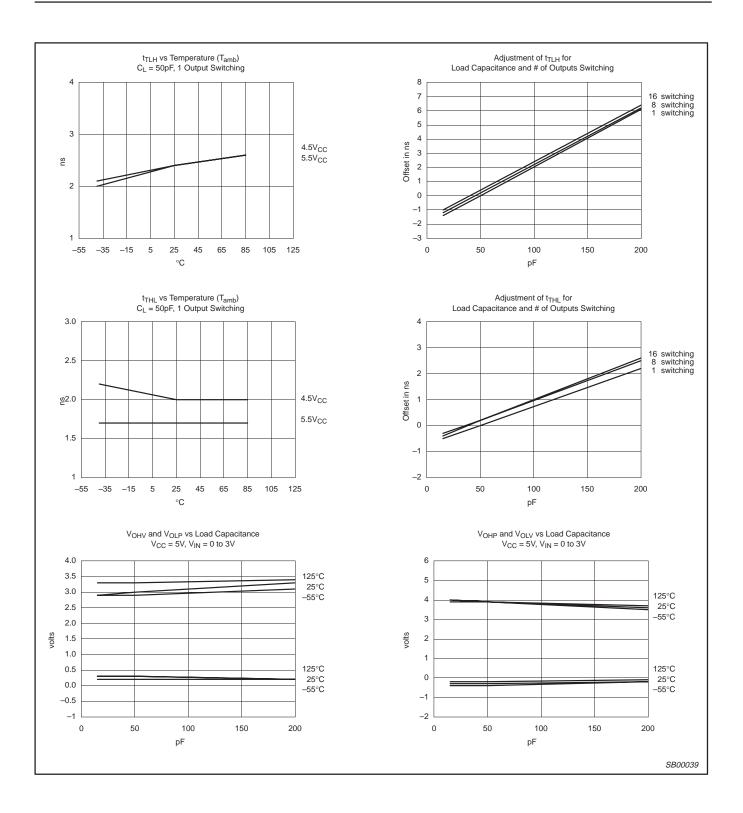


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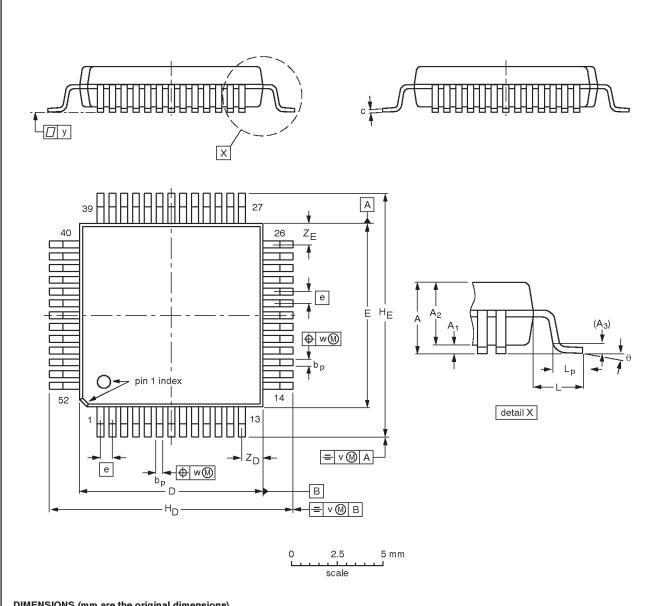
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### QFP52: plastic quad flat package; 52 leads (lead length 1.6 mm); body 10 x 10 x 2.0 mm

SOT379-1



### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	А3	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	H <sub>D</sub>	HE	L	Lp	٧	w	у	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
mm	2.45	0.45 0.25	2.10 1.95	0.25	0.38 0.22	0.23 0.13	10.1 9.9	10.1 9.9	0.65	13.45 12.95		1.60	0.95 0.65	0.20	0.12	0.10	1.24 0.95	1.24 0.95	7° 0°

### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT379-1		MO-108			<del>-95-02-04-</del> 97-08-04

## 16-bit buffer/line driver (3-State)

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**NOTES** 

### 16-bit buffer/line driver (3-State)

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#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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<sup>[1]</sup> Please consult the most recently issued datasheet before initiating or completing a design.

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